

Final Product/Process Change Notification

Document #:FPCN23597ZD Issue Date:01 Feb 2022

Title of Change:	Conversion of select onsemi, Czech Republic (Roznov) wafer fab technologies from 150mm to 200mm wafer diameter - NCV2931.	
Proposed Changed Material First Ship Date:	01 Aug 2022 or earlier if approved by customer	
Current Material Last Order Date:	N/A Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.	
Current Material Last Delivery Date:	N/A The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory	
Product Category:	Active components – Integrated circuits	
Contact information:	Contact your local onsemi Sales Office or <u>Jan.Gryzbon@onsemi.com</u>	
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Sample Availability Date:	31 Jan 2022	
PPAP Availability Date:	31 Jan 2022	
Additional Reliability Data:	Contact your local onsemi Sales Office or <u>Tomas.Vajter@onsemi.com</u>	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.	
Change Category		
Category	Type of Change	
Process - Wafer Production	New wafer diameter	

Description and Purpose:

Conversion of select onsemi, Czech Republic (Roznov) wafer fab technologies from 150mm to 200mm wafer diameter. The purpose is to increase the wafer fab productivity.

The 200mm wafer process is being created at Roznov in order to get the same electrical and reliability performances as the 150mm process. This is a change in wafer diameter only; there will be no changes to assembly or test locations as a result of this changed.

A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications.

Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed onsemi standards.

onsemi recommends that customers evaluate sample units in each associated application circuit to ensure there are no unexpected electrical incompatibilities.

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Reason / Motivation for Change:	Process/Materials Change
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.

Sites Affected:

 onsemi Sites
 External Foundry/Subcon Sites

 onsemi Roznov, Czech Republic
 None

Marking of Parts/ Traceability of Change:

The affected products will be identified with date code

Reliability Data Summary:

QV DEVICE NAME: NCV317BD2TR4G

RMS# 67729 PACKAGE: D2PAK

Test	Specification	Condition	Interval	Results
HTOL	JA108	Ta= 125°C	2016 hrs	0/240
HIUL		1d= 125 C	2016 IIIS	· ·
PC	JA112	SMD only, Test @ 0 & EP		0/372
	JA113			
SAT		Test pre- and post- PC		pass
ELFR	JA018	TA = 125°C for 48 hrs	48hrs	0/2400
TC	JA104	Test @ R	500cyc	0/276
BS	AEC-Q100-001	Cpk 1.33, 30 bonds from 5units		pass
BPS	M883	2 mm Pull Favor Min After TC		pass
BPS	Method 2011	3gm Pull Force Min After TC		
ESD HBM	AEC-Q100-002		2kV	0/3
ESD MM	AEC-Q100-003	c = 0, Test @ R	200V	0/3
ESD CDM	AEC-Q100-011	c = 0, Test @ R	1kV	0/3
- FD	ON Data Sheet	Cpk > 1.67	Calo 1 C7	pass
ED		Test @ R, H, C	Cpk>1.67	
111	450 0400 004	Toot @ FD: Toot & Strong @ D	LU+>100mA	0/6
LU	AEC-Q100-004	Test @ EP; Test & Stress @ R	LU->100mA	

Electrical Characteristics Summary:

Electrical characteristics are not impacted. All Data Sheet specifications remain the same.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle	
NCV2931CDR2G	NA	NCV317BD2TG	
NCV2931AST-5T3G	NA	NCV317BD2TG	

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NCV2931ADT5.0RKG NA NCV317BI		NCV317BD2TG
NCV2931AD-5.0R2G	5.0R2G NA NCV317BD2TG	
NCV2931ACDR2G	NA	NCV317BD2TG
NCV2931ACD2TR4G	NA	NCV317BD2TG

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Appendix A: Changed Products

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Issue Date: Feb 01, 2022

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NCV2931CDR2G		NCV317BD2TG	NA	
NCV2931ADT5.0RKG		NCV317BD2TG	NA	
NCV2931AD-5.0R2G		NCV317BD2TG	NA	
NCV2931ACDR2G		NCV317BD2TG	NA	
NCV2931AST-5T3G		NCV317BD2TG	NA	